

200Gb/s QSFP-DD 1310nm LR4 10km Optical Transceiver

Features

- IEEE802.3bs compliant
- QSFP-DD MSA compliant
- 4 LWDM lanes MUX/DEMUX design
- Supports 212.5Gb/s aggregate bit rate
- Up to 10km transmission on single mode fiber (SMF) with FEC
- Operating case temp Commercial: 0°C to +70 °C
- 200GAUI-4 electrical interface
- Maximum power consumption 10.8W
- LC duplex connector
- RoHS compliant

Applications

- Data Center Interconnect
- 200G Ethernet
- Enterprise networking



General Description

This product is a 200Gb/s transceiver module designed for 10km optical communication applications. The design is compliant to IEEE802.3bs 200GBASE-LR4 standard. The module converts 8 input channels (ch) of 25Gb/s electrical data to 4 channels of LWDM optical signals, and multiplexes them into a single channel for 200Gb/s (PAM4) optical transmission. Reversely, on the receiver side, the module optically de-multiplexes a 200Gb/s (PAM4) input into 4 LWDM channels of signals, and converts them to 8 channels output electrical data.

The central wavelengths of the 4 LWDM channels. It contains a duplex LC connector for the optical interface and a 76-pin connector for the electrical interface. To minimize the optical dispersion in the long-haul system, single-mode fiber (SMF) has to be applied in this module. Host FEC is required to support up to 10km fiber transmission.

The product is designed with form factor, optical/electrical connection and digital diagnostic interface according to the QSFP-DD Multi-Source Agreement (MSA). It has been designed to meet the harshest external operating conditions including temperature, humidity and EMI interference.

Functional Description

This product converts the 8-channel of 25Gb/s electrical input data into LWDM optical signals. The transmitter path incorporates a quad channel EML driver and EML lasers together with an optical multiplexer. The light is combined by the MUX parts as a 200Gb/s data, propagating out of the transmitter module from the SMF. On the receiver path, an optical de-multiplexer is coupled to a 4 channel photo-diode array. A DSP basis gearbox is used to convert 8 channels of 25GBaud PAM4 signals into 4 channels of 8 channels of 25GBaud NRZ signals and also an 8-channel re-timer and FEC block are integrated in this DSP. The electrical interface is compliant with IEEE 802.3bs and QSFP-DD MSA in the transmitting and receiving directions, and the optical interface is compliant to IEEE 802.3bs with duplex LC connector.

A single +3.3V power supply is required to power up this product. Both power supply pins VccTx and VccRx are internally connected and should be applied concurrently. As per MSA specifications—the module offers 7 low speed hardware control pins (including the 2-wire serial interface): ModSelL, SCL, SDA, ResetL, LPMode, ModPrsL and IntL.

Module Select (ModSelL) is an input pin. When held low by the host, this product responds to 2-wire serial communication commands. The ModSelL allows the use of this product on a single 2-wire interface bus – individual ModSelL lines must be used.

Serial Clock (SCL) and Serial Data (SDA) are required for the 2-wire serial bus communication interface and enable the host to access the QSFP+ memory map.

The ResetL pin enables a complete reset, returning the settings to their default state, when a low level on the ResetL pin is held for longer than the minimum pulse length. During the execution of a reset the host shall disregard all status bits until it indicates a completion of the reset interrupt. The product indicates this by posting an IntL (Interrupt) signal with the Data_Not_Ready bit negated in the memory map. Note that on power up (including hot insertion) the module should post this completion of reset interrupt without requiring a reset.

Low Power Mode (LPMode) pin is used to set the maximum power consumption for the product in order to protect hosts that are not capable of cooling higher power modules, should such modules be accidentally inserted.



Module Present (ModPrsL) is a signal local to the host board which, in the absence of a product, is normally pulled up to the host Vcc. When the product is inserted into the connector, it completes the path to ground through a resistor on the host board and asserts the signal. ModPrsL then indicates its present by setting ModPrsL to a "Low" state.

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Interrupt (IntL) is an output pin. "Low" indicates a possible operational fault or a status critical to the host system. The host identifies the source of the interrupt using the 2-wire serial interface. The IntL pin is an open collector output and must be pulled to the Host Vcc voltage on the Host board.

Absolute Maximum Ratings

Table1	-Absol	ute Maxii	mum Ratings

Parameter	Symbols	Min.	Typical	Max.	Unit	Notes		
Storage Temperature	TS	-40		+85	degC			
Operating Case Temperature	TOP	0		70	degC			
Power Supply Voltage	VCC	-0.5		3.6	V			
Relative Humidity(non-condensation)	RH	0		85	%			
Damage Threshold, each Lane	THd	6.3			dBm			

Recommended Operating Conditions

Tablez-Recommended Operating Conditions									
Parameter	Symbols	Min.	Typical	Max.	Unit	Notes			
Operating Case Temperature	Тор	0		+70	degC				
Power Supply Voltage	VCC	3.135	3.3	3.465	V				
			26.5625		GBd				
Data Rate, each Lane			53.125		Gb/s				
Data Rate Accuracy		-100		100	ppm				
Pre-FEC Bit Error Ratio				2.4x10-4					
Post-FEC Bit Error Ratio				1x10-12		1			
Control Input Voltage High		2		VCC	V				
Control Input Voltage Low		0		0.8	V				
Link Distance with G.652	D	0.002		10	km	2			

Notes:

[1]FEC provided by host system.

[2]FEC required on host system to support maximum distance.



Optical Characteristic

Parameter	Symbol	Min.	Typical	Max.	Unit	Notes
Supply current	lcc				mA	
Power Consumption				10.8	W	
	L0	1294.53		1296.59	nm	
	L1	1299.02		1301.09	nm	
Wavelength Assignment	L2	1303.54		1305.63	nm	
	L3	1308.09		1310.19	nm	
	Tra	nsmitter				
Data Rate, each Lane			26.5625 ± 100	ppm	GBd	
Modulation Format		PAM4				
Side-mode Suppression Ratio	SMSR	30			dB	Modulate
Total Average Launch Power	PT	2.6		11.3	dBm	
Average Launch Power, each Lane	PAVG	-3.4		5.3	dBm	1
Outer Optical Modulation Amplitude (OMA _{outer}), each Lane	POMA	-0.4		5.1	dBm	2
Launch Power in OMA _{oute} r minus TDECQ, each Lane		-1.8			dB	For ER ≥4.5dE
		-1.7			dB	For ER
Transmitter and Dispersion Eye Closure for PAM4, each Lane	TDECQ			3.2	dB	
Extinction Ratio	ER	3.5			dB	
Difference in Launch Power between any Two Lanes (OMA _{outer})				4	dB	
RIN16.50MA	RIN			-132	dB/Hz	
Optical Return Loss Tolerance	TOL			15.6	dB	
Transmitter Reflectance	TR			-26	dB	
Average Launch Power of OFF Transmitter, each Lane	P_{off}			-30	dBm	



Data Rate, each Lane		26.5625 ± 100 ppm			GBd	
Modulation Format		PAM4				
Damage Threshold, each Lane	THd	6.3			dBm	3
Average Receive Power, each Lane		-9.7		5.3	dBm	4
Receive Power (OMA _{outer}), each Lane				5.1	dBm	
Difference in Receiver Power between any Two Lanes (OMA _{outer})				4.2	dB	
Receiver Sensitivity (OMA _{outer}), each Lane	SEN			max (7.2 ,SECQ -8.6)	dBm	For BER of 2.4E-4
Stressed Receiver Sensitivity (OMA _{outer}), each Lane	SRS			-5,4	dBm	5
Receiver Reflectance	RR			-26	dB	
LOS Assert	LOSA	-25.7			dBm	
LOS De-assert	LOSD			-11.7	dBm	
LOS Hysteresis	LOSH	0.5			dB	

Notes:

- [1] Average launch power, each lane (min) is informative and not the principal indicator of signal strength. A transmitter with launch power below this value cannot be compliant; however, a value above this does not ensure compliance.
- [2] Even if the TDECQ <1.4 dB for an extinction ratio of \geq 4.5 dB or TDECQ <1.3 dB for an extinction ratio of <4.5 dB, the OMA_{outer} (min) must exceed the minimum value specified here.
- [3] The receiver shall be able to tolerate, without damage, continuous exposure to an optical input signal having this average power level.
- [4] Average receive power, each lane (min) is informative and not the principal indicator of signal strength. A received power below this value cannot be compliant; however, a value above this does not ensure compliance.
- [5] Measured with conformance test signal for BER = $2.4x10^{-4}$.
- [6] These test conditions are for measuring stressed receiver sensitivity. They are not characteristics of the receiver.

Electrical Characteristic

Table4-Electrical Characteristic							
Parameter	Symbols	Min.	Typical	Max.	Unit	Notes	
Power Consumption				10.8	W		
Supply Current	lcc				mA		
	Tr	ansmitter (eacl	h Lane)				
Overload Differential Voltage pk-pk	TP1a			900	mV		
Common Mode Voltage (Vcm)	TP1	-300		2800	mV		
		Receiver (each	Lane)				



Differential Voltage, pk-pk	TP4		900	mV	
Power Consumption			10.8	W	
Supply Current	lcc			mA	

Digital Diagnostic Functions

Table5- Digital Diagnostic Functions						
Parameter	Symbols	Min.	Max.	Unit	Notes	
Temperature monitor absolute error	DMI_Temp	-3	3	degC	Over operating temperature range	
Supply voltage monitor absolute error	DMI_VCC	-0.1	0.1	V	Over full operating range	
Channel RX power monitor absolute error	DMI_RX_Ch	-3	3	dB	1	
Channel Bias current monitor	DMI_Ibias_Ch	-10%	10%	mA		
Channel TX power monitor absolute error	DMI_TX_Ch	-3	3	dB	1	

Notes:

^[1] Due to measurement accuracy of different single mode fibers, there could be an additional +/-1 dB fluctuation, or a +/- 3 dB total accuracy.



Pin Description

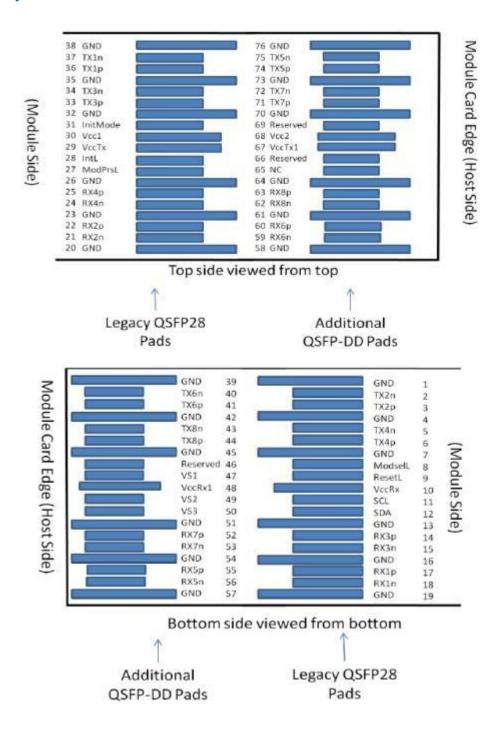


Figure 1 Pin view

Pin Function Definitions

Table6- Pin Function Definitions							
Pin	Symbols	Description	Notes				



1	GND	Ground	1
2	Tx2n	Transmitter Inverted Data Input	
3	Tx2p	Transmitter Non-Inverted Data Input	
4	GND	Ground	1
5	Tx4n	Transmitter Inverted Data Input	
6	Tx4p	Transmitter Non-Inverted Data Input	
7	GND	Ground	
8	ModSelL	Module Select	
9	ResetL	Module Reset	
10	Vcc Rx	+3.3V Power Supply Receiver	2
11	SCL	2-wire serial interface clock	
12	SDA	2-wire serial interface data	
13	GND	Ground	
14	Rx3p	Receiver Non-Inverted Data Output	
15	Rx3n	Receiver Inverted Data Output	
16	GND	Ground	1
17	Rx1p	Receiver Non-Inverted Data Output	
18	Rx1n	Receiver Inverted Data Output	1
19	GND	Ground	1
20	GND	Ground	
21	Rx2n	Receiver Inverted Data Output	
22	Rx2p	Receiver Non-Inverted Data Output	
23	GND	Ground	
24	Rx4n	Receiver Inverted Data Output	
25	Rx4p	Receiver Non-Inverted Data Output	
26	GND	Ground	1
27	ModPrsL	Module Present	
28	IntL	Interrupt	
29	VccTx	+3.3V Power supply transmitter	2
30	Vcc1	+3.3V Power supply	2
31	LPMode	Low Power Mode	
32	GND	Ground	1
33	Tx3p	Transmitter Non-Inverted Data Input	
34	Tx3n	Transmitter Inverted Data Input	
35	GND	Ground	1
36	Tx1p	Transmitter Non-Inverted Data Input	
37	Tx1n	Transmitter Inverted Data Input	
38	GND	Ground	1

Notes:

[1]GND is the symbol for signal and supply (power) common for QSFP-DD modules. All are common within the QSFP-DD module and all module voltages are referenced to this potential unless otherwise noted. Connect these directly to the host board signal common ground plane.



[2]VccRx, Vcc1 and VccTx are the receiving and transmission power suppliers and shall be applied concurrently. Recommended host board power supply filtering is shown in Figure 3 below. Vcc Rx, Vcc1 and Vcc Tx may be internally connected within the QSFP-DD transceiver module in any combination. The connector pins are each rated for a maximum current of 1000mA.

Transceiver Block Diagram

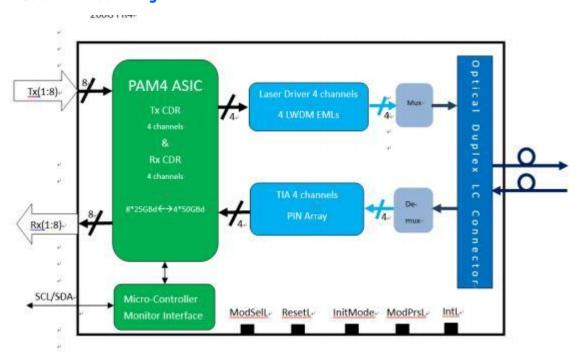


Figure 2 Transceiver Block Diagram



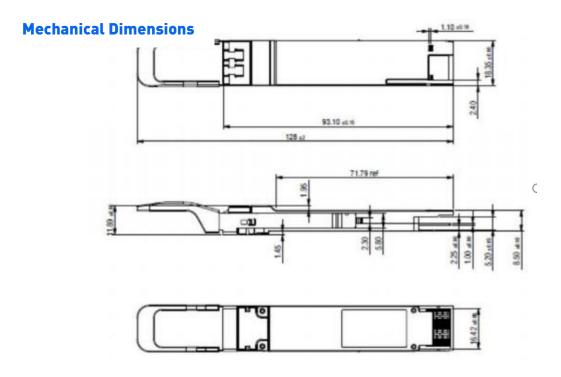


Figure 3 Mechanical Outline

ESD

This transceiver is specified as ESD threshold 1kV for high speed data pins and 2kV for all other electrical input pins, tested per MIL-STD-883, Method 3015.4 /JESD22-A114-A (HBM). However, normal ESD precautions are still required during the handling of this module. This transceiver is shipped in ESD protective packaging. It should be removed from the packaging and handled only in an ESD protected environment.

Laser Safety

This is a Class 1 Laser Product according to EN 60825-1:2014. This product complies with 21 CFR 1040.10 and 1040.11 except for deviations pursuant to Laser Notice No. 50, dated (June 24, 2007).

Caution: Use of controls or adjustments or performance of procedures other than those specified herein may result in hazardous radiation exposure.



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